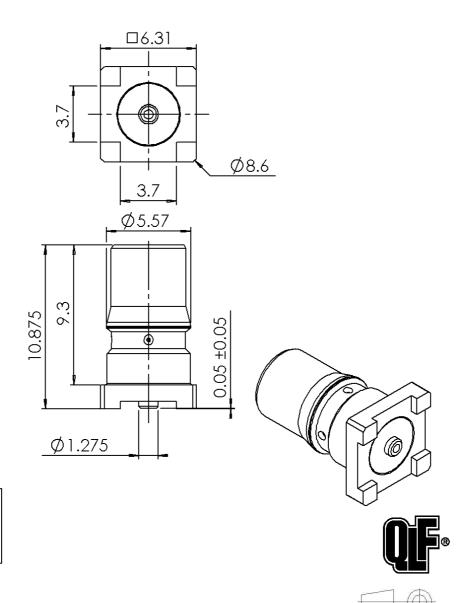
REEL 300

R123.427.823

Series : **QMA**



All dimensions are in mm.

Ech: 1

		$\rightarrow \rightarrow \rightarrow$
 COMPONENTS	MATERIALS	PLATING (μm)
BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS -	BRASS BERYLLIUM COPPER PTFE	NPGR NPGR

Issue: 0923 D

In the effort to improve our products, we reserve the right to make changes judged to be



REEL 300

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Series: QMA

PACKAGING

Standard	Unit	Other
300		Contact us

SPECIFICATION

ELECTRICAL CHARACTERISTICS

Impedance 50 Ω Frequency **0-6** GHz

VSWR $1.04 + 0.0450 \times F(GHz) Maxi$

Insertion loss **0.05** $\sqrt{F(GHz)}$ dB Maxi

RF leakage **80** - F(GHz)) dB Maxi - (

Voltage rating 500 Veff Maxi Dielectric withstanding voltage 1000 Veff mini Insulation resistance **5000** M Ω mini

ENVIRONMENTAL

-40/+105 ° C Operating temperature

Hermetic seal NA Atm.cm3/s

Panel leakage NA

OTHER CHARACTERISTICS

Assembly instruction

Others:

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end 27 N mini Axial force – Opposite end 27 N mini Torque 2.8 N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 100 Cycles mini

Weight **1,2180** g Intermod.:-120dBc at 1.8GHz(2 x 20W) RF leakage:Interf. only:3<F<6GHz:>70dB

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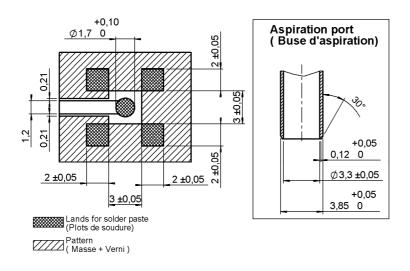
R123.427.823

Series: QMA

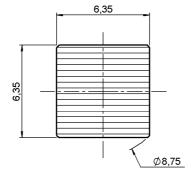
QMA SERIE - INFORMATIONS

COPLANAR LINE: Pattern and signal are on the same side. Thickness of PCB = 0.063 (1.6mm).

The material of PCB is the epoxy resin of glass fabrics bacs (Er = 4.8). The solder resist should be printed except for the land pattern on the PCB.



SHADOW OF QMA RECEPTACLE FOR VIDEO CAMERA



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necessary.



REEL 300

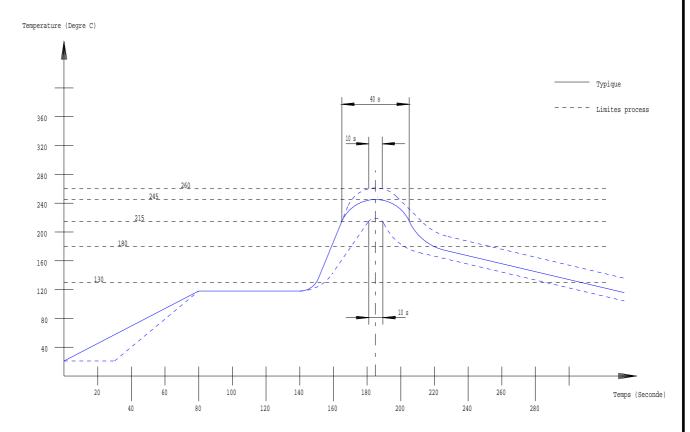
R123.427.823

Series: QMA

SOLDER PROCEDURE

- 1. Deposit solder paste 'SN62RP11AGS90' on mounting zone by screen printing application. We recommend a low residue flux.
 - We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.
- 2. Placement of the receptacle on the mounting zone with an automatic 'pick and place' machine. Video camera is preferred to check the positioning of the component (See page 3). Adhesive agents are forbidden on the receptacle.
- 3. Soldering by infra-red reflow. We give under, the typical profile to use.
- 4. Cleaning of the printed circuits board.
- 5. Checking of solder joints and position of the components by visual inspection.

TEMPERATURE PROFIL



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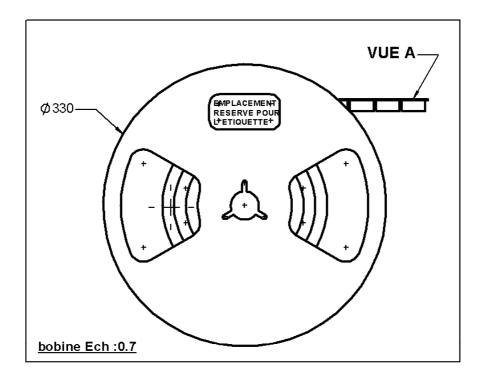
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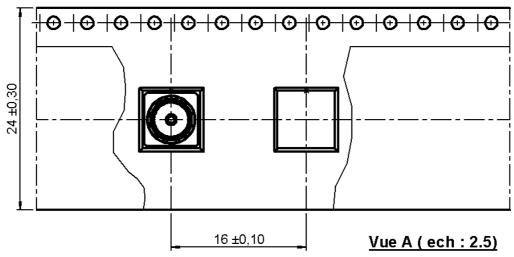


REEL 300

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